

LOCTITE ABLESTIK QMI546

April 2014

PRODUCT DESCRIPTION

LOCTITE ABLESTIK QMI546 provides the following product characteristics:

Technology	BMI	
Appearance	White paste	
Filler Type	Fluoropolymer	
Product Benefits	Non-conductive	
	Hydrophobic	
	 Stable at high temperatures 	
	Void-free bondline	
	No pre-drying	
	Excellent dielectric properties	
Cure	Skip-Cure Process	
Application	Die attach	
Substrates	PBGA, CSPs, Die Stack, Organic	
	Laminate and Flexible tape	
Surface Finishes	Solder Mask, BT, FR, Polyimide, Au and	
	Other organic surfaces	

LOCTITE ABLESTIK QMI546 die attach adhesive is formulated to cure rapidly below the boiling point of water, preventing steam from creating voids. This product is designed to achieve UPHs several orders of magnitude higher than conventional oven cured adhesives.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity @ 25 °C, mPa·s (cP):	
Speed 5 rpm	6,500
Thixotropic Index (0.5/5 rpm)	6.0
Specific Gravity @ 25°C	1.3
Pot life @ 25 °C, hours	24
Shelf Life @ -40°C, days	365
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE

SkipCure Process

≥8 seconds @ 150°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Coefficient of Thermal Expansion, TMA:	
Below Tg, ppm/°C	80
Above Tg, ppm/°C	190
Glass Transition Temperature (Tg), °C	10
DMA Modulus	GPa 1.0 (N/mm²) (1,000) (psi) (145,000)
Thermal Conductivity , W/(m-K)	0.2

Extractable Ionic Content, ppm:	
Sodium (Na+)	≤20
Potassium (K+)	≤20
Chloride (Cl-)	≤20
Fluoride (F-)	≤20
Moisture Absorption, 168 hours @ 85°C/85% RH, wt.%	<0.3
Alpha Particle Emissions, particles/cm ² /hr	<0.001
Electrical Dransmiss	
Electrical Properties	
Dielectric Constant @ 1 MHz, @ 25 °C	2.6
Volume Resistivity, Ω.cm	>1×10 ¹³

TYPICAL PERFORMANCE OF CURED MATERIAL

Miscellaneous

Die Shear Strength @ 25 °C:	
7.62 x 7.62 mm, 0.254 mm BLT, kg-f	20

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

THAWING:

- 1. Allow container to reach room temperature before use.
- 2. After removing from the freezer, set the syringes to stand vertically while thawing.
- DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- 4. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.

Directions for use

- LOCTITE ABLESTIK QMI546 has excellent rheology and flow easily under shear stresses such as those present during die bonding.
- 2. Therefore, bond forces used with other adhesive which product a certain product bond line thickness, may result in thinner bond line with LOCTITE ABLESTIK QMI546.
- 3. Optimization of diebonding parameters is strongly recommended to consistently meet target bondline thickness.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage : -40 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If



additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

 $(^{\circ}C x 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa = N/mm² MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference 0.1